

NEWS RELEASE

STABLCOR TECHNOLOGY, INC. AWARDED LAMINATE AND PROCESS PATENT IN TAIWAN

Huntington Beach, CA – June 26, 2013 – StablcOR Technology, Inc. is pleased to announce the acceptance of **STABLCOR®** laminate and processing technology by the Taiwanese Patent Office. The acceptance of **“BUILD-UP PRINTED WIRING BOARD SUBSTRATE HAVING A CORE LAYER THAT IS PART OF A CIRCUIT”** further strengthens our portfolio within Asia and our commitment to enhance the **STABLCOR®** Technology within Taiwan, and abroad.

About StablcOR Technology, Inc.

StablcOR Technology, Inc. is an Intellectual Property company and the only provider of **STABLCOR®**, a thermally and electrically conductive carbon composite material which, when incorporated within printed circuit boards and substrates, controls heat, thermal expansion, increases rigidity and strength, with no weight premium. The patented laminate and processes to incorporate **STABLCOR®** into printed circuit boards and substrates provides the electronic industry a cost efficient technology to produce smaller electronic products while eliminating the thermal, mechanical, and reliability concerns that currently challenge the semiconductor industry. For more information about **STABLCOR®** visit our website at www.stablcOR.com.

CONTACT:

Doug Schneider
President and CEO
(714) 375-6644
dougschneider@stablcOR.com